

Please amend the **Specification** as follows:

Please amend the title as follows:

METHOD OF MAKING A CENTER BOND FLIP CHIP SEMICONDUCTOR  
~~CARRIER AND A METHOD OF MAKING AND USING IT~~

At page 1, after the title, please insert --This application is a divisional of application Ser. No. 09/680,473, filed on October 6, 2000, now U.S. Patent No. \_\_\_\_\_, which is a divisional of application Ser. No. 09/469,630, filed on December 22, 1990, now U.S. Patent No. 6,431,102, which are hereby incorporated by reference in their entirety.--

Please replace the paragraph starting at page 5, line 18 as follows:

FIG. 5 is a cross-sectional view taken along line V-V of the semiconductor device of FIG. 4 3.

Please replace the paragraph starting at page 5, line 20 as follows:

FIG. 6 is a cross-sectional view taken along line VI-VI of the semiconductor device of FIG. 4 3.